



CBR-SMD RF COG, Ceramic, 4.3 pF, +/-0.05 pF, 25 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0402



General Information	
Series	CBR-SMD RF COG
Style	SMD Chip
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I
Features	Ultra High Q, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	1.37 mg
Notes	Solder Reflow Only.
Shelf Life	78 Weeks
MSL	1

4.3 pF +/-0.05 pF

Dimensions	
Chip Size	0402
L	1mm +/-0.05mm
W	0.5mm +/-0.05mm
Т	0.5mm +/-0.05mm
В	0.25mm +0.05/-0.1mm

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0.5mm +/-0.05mm	Voltage DC	25 VDC
0.5mm +/-0.05mm	Dielectric Withstanding Voltage	62.5 VDC
0.25mm +0.05/-0.1mm	Temperature Range	-55/+125°C
	Temp. Coefficient	COG
	Dissipation Factor	0.206%
T&R, 180mm, Plastic Tape	Aging Rate	0% Loss/Decade Hour
10000	Insulation Resistance	10 GOhms
	0.5mm +/-0.05mm 0.25mm +0.05/-0.1mm T&R, 180mm, Plastic Tape	0.5mm +/-0.05mm Dielectric Withstanding Voltage 0.25mm +0.05/-0.1mm Temperature Range Temp. Coefficient Dissipation Factor T&R, 180mm, Plastic Tape Aging Rate

Specifications Capacitance

Tolerance

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and
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